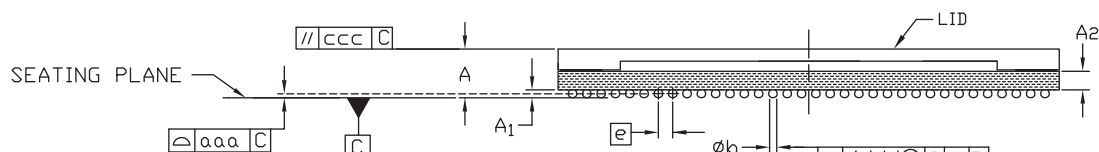
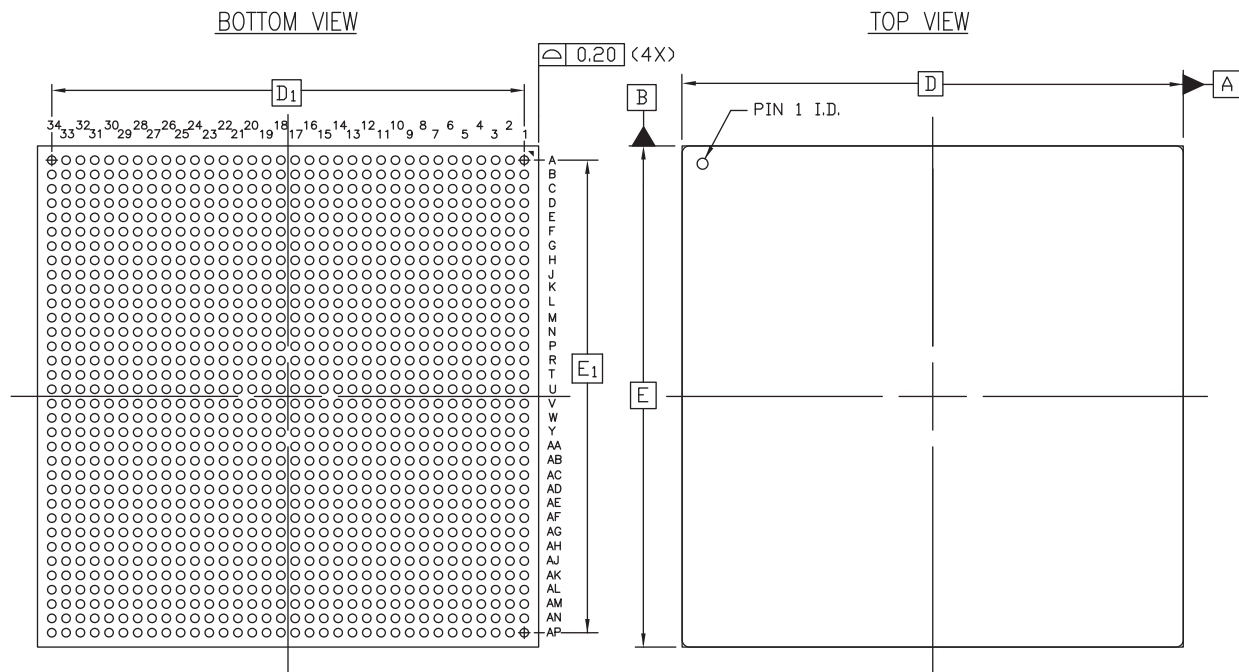


1156 Ball Flip-Chip BGA (FF1154/FFG1154) Package



FF1154 - Sn/Pb SOLDER BALLS
FFG1154 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.70	2.70	3.50	
A ₁	0.40	0.50	0.60	
A ₂	0.90	0.90	1.50	
D/E	35.00 BASIC			
D ₁ /E ₁	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	0.20	0.20	0.20	
ccc	0.35	0.35	0.35	
ddd	0.25	0.25	0.25	
eee	0.10	0.10	0.10	
M	34			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAR-1
4. ACTUAL SOLDER BALL COUNT = 1156

pk392_01_110909

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/09/09	1.0	Initial Xilinx release.

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